

A

B

C

D

E

REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
X1			INITIAL RELEASE	12/2'19	Wanglie
X2			ADD RECOMMENDED MODULE CARD	03/11'20	Mike Jiang

1. MATERIAL:

1.1 HOUSING: HIGH TEMPERATURE THERMO PLASTIC UL94V-0;

COLOR: BLACK

1.2 CONTACT: COPPER ALLOY

1.3 LATCH:STAINLESS

2. FINISH:

2.1 CONTACT:

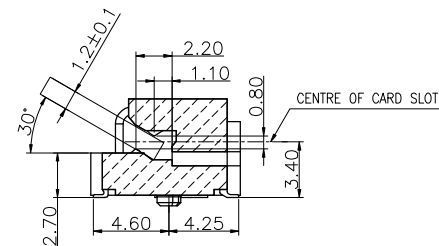
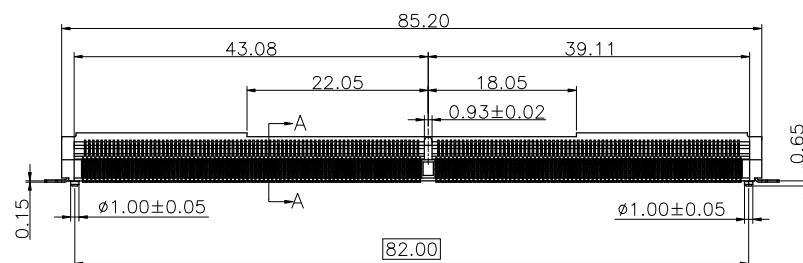
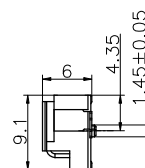
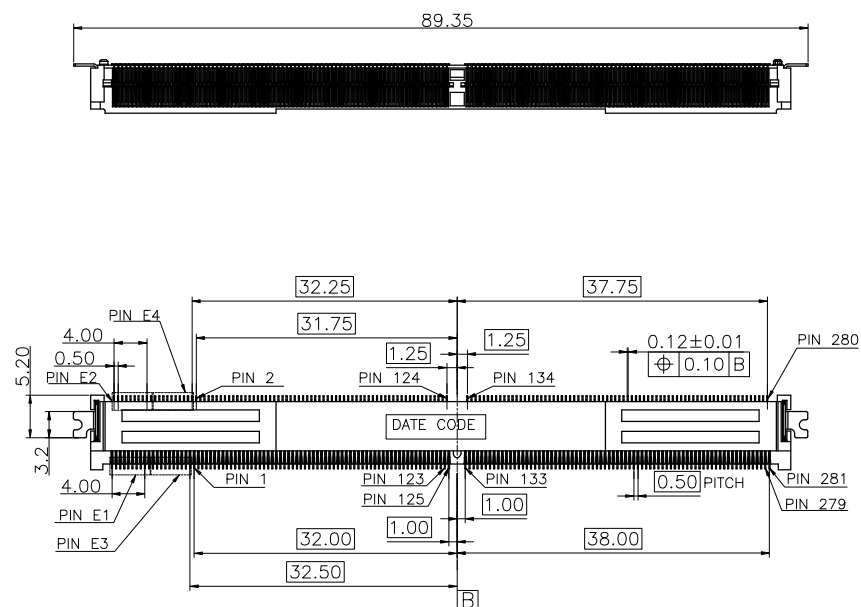
CONTACT AREA: GOLD PLATING(THICKNESS SEE TABLE).

SOLDER AREA: GLOD FLASH

1.27um[50u"] MIN. NICKEL UNDERPLATING OVERALL.

2.2 LATCH: 1.27um[50u"] MIN. MATTE TIN PLATING.

3. REFLOW SOLDER CAPABLE TO 260°C MAX.



SECTION:A-A

SCALE 2:1

TABLE

5u" Au	A10569H02001H
PLATING THICKNESS	DEREN P/N

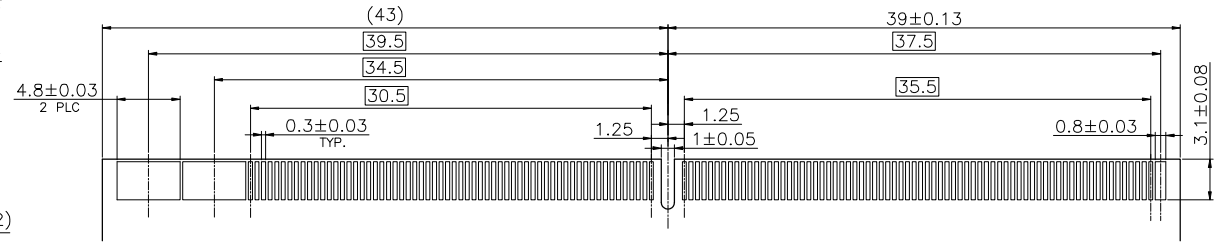
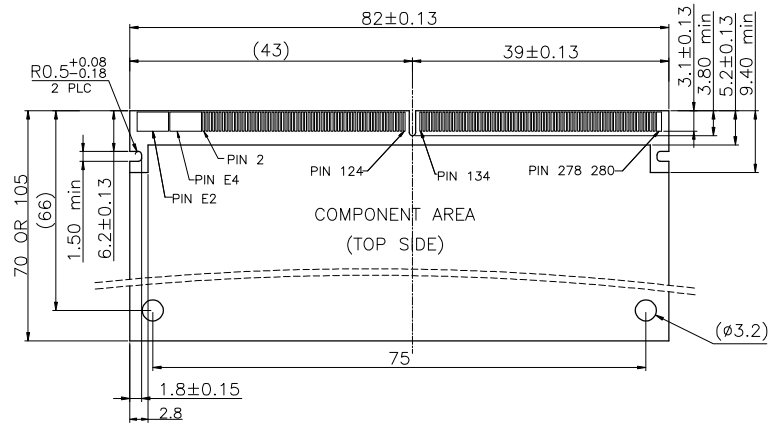
DIM		TOL				CUSTOMER DRAWING DATE		TITLE: MXM 6.0H 314P SMT TYPE P/N: A10569H02001H	
.X	±0.30	.x	±2*						
.X	±0.25	.X	±1*						
.XX	±0.15								
				DRAW NO.		DESIGN:		Mike Jiang	
				SC2006384		CHECK:		Bill.lin	
				REV.		X2		APPROVAL:	
						Bill.lin		03/11/20	
								SHEET: 1/4	
								SCALE: 1:1	
								UNIT: mm	

HF

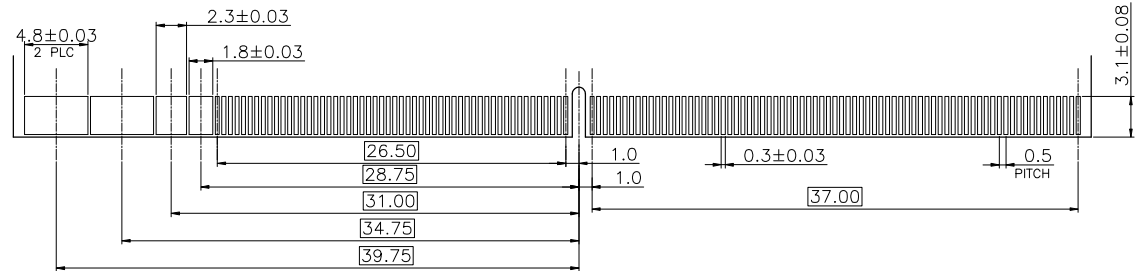
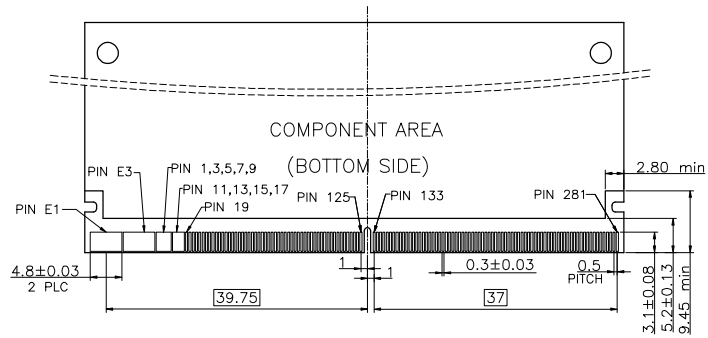
Halogen Free

RECOMMENDED MODULE CARD

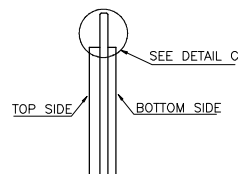
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
X1			INITIAL RELEASE	12/2'19	Wanglie
X2			ADD RECOMMENDED MODULE CARD	03/11'20	Mike Jiang



TOP SIDE
SCALE 2:1

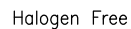


BOTTOM SIDE
SCALE 2:1

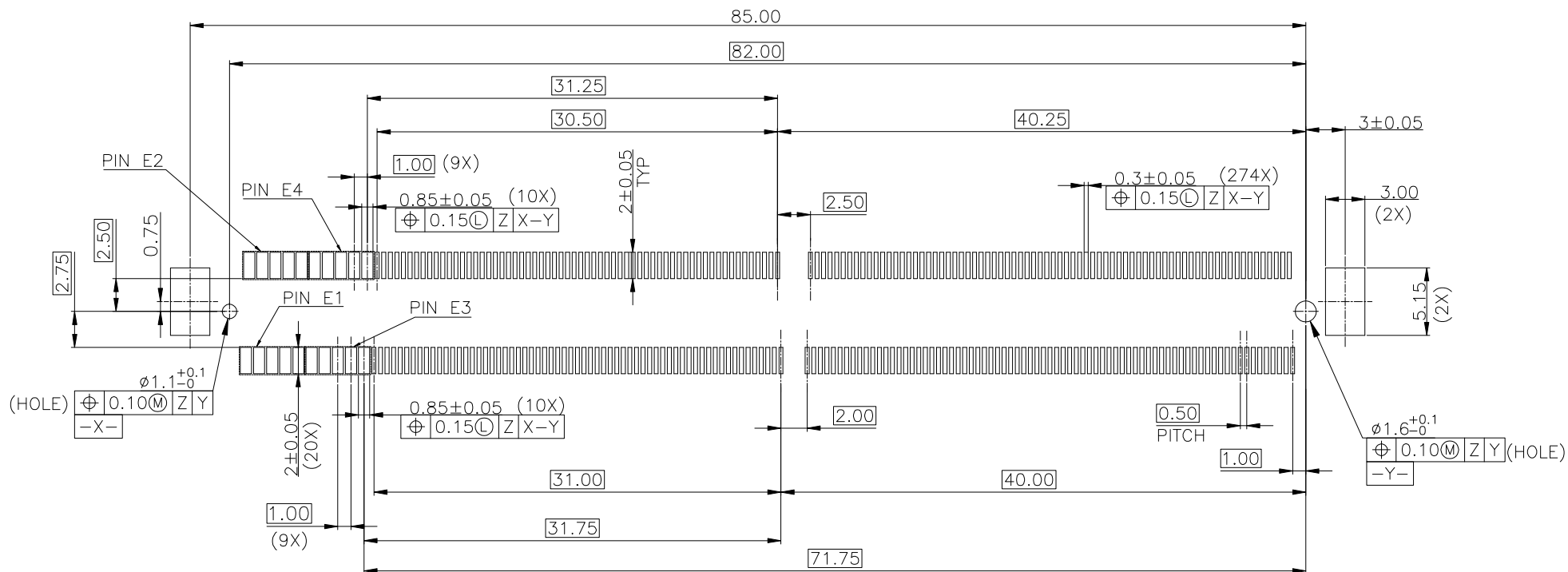


DETAIL C
SCALE 2:1

DIM	TOL	DIM	TOL	CONSHARE			
x.	± 0.30	x.	$\pm 2^\circ$	CUSTOMER DRAWING			
.x	± 0.25	.x	$\pm 1^\circ$	DESIGN:	Mike Jiang	03/11'20	TITLE: MXM 6.0H 314P SMT TYPE
.xx	± 0.15			CHECK:	Bill.lin	03/11'20	P/N: A10569H02001H
				APPROVAL:	Bill.lin	03/11'20	SHEET: 2/4
				REV. X2			SCALE: 1:1
							UNIT: mm



REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
X1			INITIAL RELEASE	12/2'19	Wanglie
X2			ADD RECOMMENDED MODULE CARD	03/11'20	Mike Jiang



RECOMMENDED PCB LAYOUT

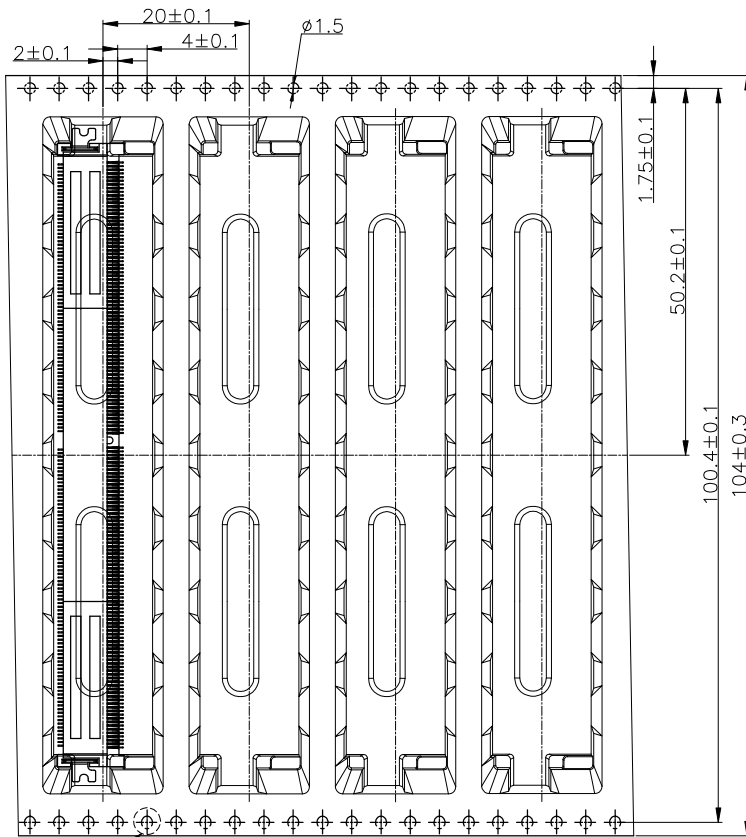
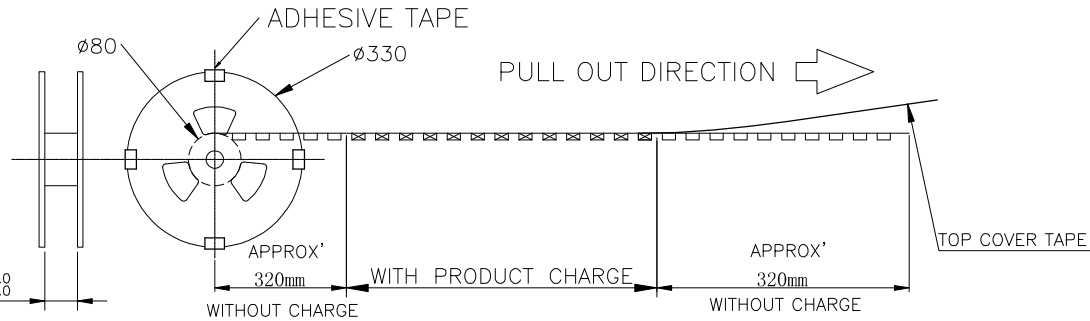
TOP VIEW

DIM		TOL		DIM		TOL									
x.		±0.30		x.		±2°		CUSTOMER DRAWING		DATE		TITLE: MXM 6.0H 314P SMT TYPE			
.x		±0.25		.x		±1°		DRAW NO. SC2006384		DESIGN: Mike Jiang		03/11'20		P/N: A10569H02001H	
.xx		±0.15						CHECK: Bill.lin		03/11'20		SHEET: 3/4			
								REV. X2		APPROVAL: Bill.lin		03/11'20		SCALE: 2:1 UNIT: mm	

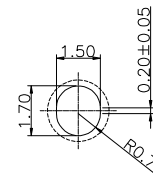
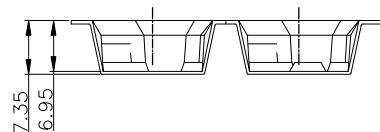


HF

Halogen Free



DETAIL A



DETAIL A
SCALE 4:1

NOTES :

PACKAGING MATERIAL IN PLASTIC, RUBBER, INK, PIGMENT AND PAINT
MUST MEET DEREN CONTROLLED SUBSTANCES SPEC.

* CADMIUM AND CADMIUM COMPOUNDS NOT TO EXCEED:
5 PPM.

* LEAD, CADMIUM, CHROM VI AND MERCURY NOT TO EXCEED:
100 PPM (COMBINED).

* CARRIER TAPES, COVER TAPES, REELS AND TAPED COMPONENTS
MUST MEET THE REQUIREMENTS DEFINED PER EIA-481-B.

1. MATERIAL :

COVER TAPE : ANTISTATIC POLYESTER , COLOR: CLEAR

CARRIER TAPE : HIPS

REEL : PS

SHIPPING BOX: CORRUGATED FIBER

2. DIMENSION :

REEL : SEE DRAWING

BOX : SEE DRAWING

3. QUANTITY : SEE TABLE

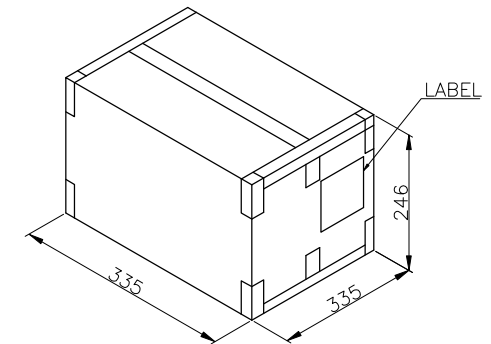
4. WEIGHT : SEE TABLE

5. PEELING RESISTANCE : 10gf~100gf (for 8mm)

10gf~130gf (for 12mm~56mm)

10gf~150gf (for 72mm)

6. PEELING SPEED : 300mm/MINUTES



450	2	900	A10569H02001H
PCS/ REEL	REEL/ CARTON	PCS/ CARTON	PART NUMBER

DIM	TOL	DIM	TOL	CUSTOMER DRAWING				DATE		TITLE: MXM 6.0H 314P SMT TYPE	
.X	$\pm$ 0.30	.X	$\pm$ 2°	DRAW NO. SC2006384		DESIGN:	Mike Jiang	03/11'20		P/N: A10569H02001H	
.X	$\pm$ 0.20	.X	$\pm$ 1°			CHECK:	Bill.lin	03/11'20		SHEET: 4/4	
.XX	$\pm$ 0.15			REV.	X2	APPROVAL:	Bill.lin	03/11'20		SCALE: 1:1	
										UNIT: mm	

CONSHARE